3.3 V/5 V ECL D Flip-Flop with Reset and Differential Clock

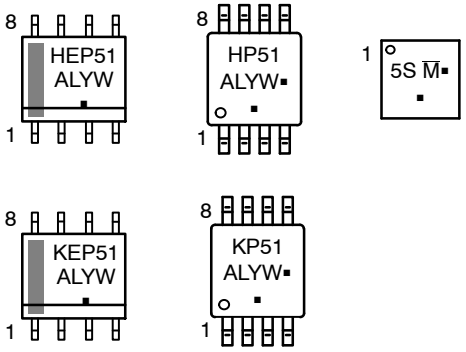
MC10EP51, MC100EP51

SOIC−8
D SUFFIX
CASE 751

TSSOP−8
DT SUFFIX
CASE 948R

DFN8
MN SUFFIX
CASE 506AA

MARKING DIAGRAM



H = MC10
K = MC100
5S = MC10
M = Date Code
A = Assembly Location
L = Wafer Lot
Y = Year
W = Work Week
▪ = Pb−Free Package

(Note: Microdot may be in either location)

*For additional marking information, refer to Application Note AND8002/D.

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page page 8 of this data sheet.

NOTE: Some of the device on this data sheet have been **DISCONTINUED**. Please refer to the table on page 8.

Description

The MC10/100EP51 is a differential clock D flip−flop with reset. The device is functionally equivalent to the EL51 and LVEL51 devices.

The reset input is an asynchronous, level triggered signal. Data enters the master portion of the flip−flop when the clock is LOW and is transferred to the slave, and thus the outputs, upon a positive transition of the clock. The differential clock inputs of the EP51 allow the device to be used as a negative edge triggered flip-flop.

The differential input employs clamp circuitry to maintain stability under open input conditions. When left open, the CLK input will be pulled down to V_{EE} and the $\overline{CLK}$ input will be biased at $V_{CC}/2$.

The 100 Series contains temperature compensation.

Features

- 350 ps Typical Propagation Delay
- Maximum Frequency > 3 GHz Typical
- PECL Mode Operating Range: V_{CC} = 3.0 V to 5.5 V with V_{EE} = 0 V
- NECL Mode Operating Range: V_{CC} = 0 V with V_{EE} = −3.0 V to −5.5 V
- Open Input Default State
- Safety Clamp on Inputs
- These Devices are Pb−Free and are RoHS Compliant

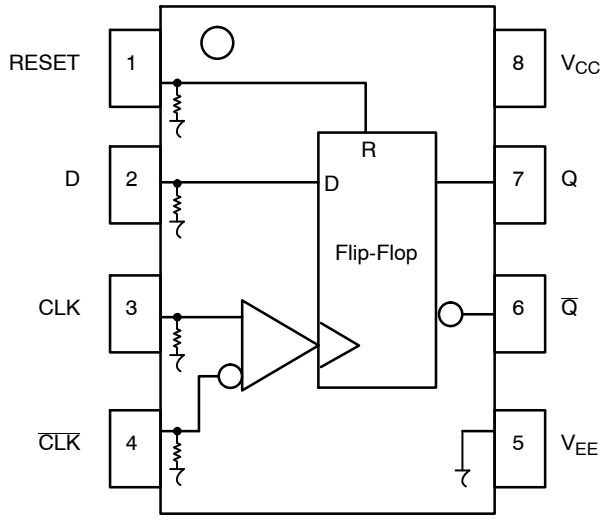


Figure 1. 8−Lead Pinout (Top View) and Logic Diagram

Table 1. PIN DESCRIPTION

PIN	FUNCTION
CLK*, $\overline{CLK}$*	ECL Clock Inputs
Reset*	ECL Asynchronous Reset
D*	ECL Data Input
Q, $\overline{Q}$	ECL Data Outputs
V_{CC}	Positive Supply
V_{EE}	Negative Supply
EP	(DFN8 only) Thermal exposed pad must be connected to a sufficient thermal conduit. Electrically connect to the most negative supply (GND) or leave unconnected, floating open.

* Pins will default LOW when left open.

Table 2. TRUTH TABLE

D	R	CLK	Q
L	L	Z	L
H	L	Z	H
X	H	X	L

Z = LOW to HIGH Transition

Table 3. ATTRIBUTES

Characteristics	Value
Internal Input Pulldown Resistor	75 kΩ
Internal Input Pullup Resistor	N/A
ESD Protection Human Body Model Machine Model Charged Device Model	> 2 kV > 200 V > 2 kV
Moisture Sensitivity, Indefinite Time Out of Drypack (Note 1)	Pb−Free Pkg
SOIC−8 TSSOP−8 DFN8	Level 1 Level 3 Level 1
Flammability Rating Oxygen Index: 28 to 34	UL 94 V−0 @ 0.125 in
Transistor Count	165 Devices
Meets or exceeds JEDEC Spec EIA/JESD78 IC Latchup Test	

1. For additional information, see Application Note AND8003/D.

Table 4. MAXIMUM RATINGS

Symbol	Parameter	Condition 1	Condition 2	Rating	Unit
V_{CC}	PECL Mode Power Supply	V_{EE} = 0 V		6	V
V_{EE}	NECL Mode Power Supply	V_{CC} = 0 V		−6	V
V_I	PECL Mode Input Voltage NECL Mode Input Voltage	V_{EE} = 0 V V_{CC} = 0 V	$V_I \le V_{CC}$ $V_I \ge V_{EE}$	6 −6	V V
I_{out}	Output Current	Continuous Surge		50 100	mA mA
T_A	Operating Temperature Range			−40 to +85	°C
T_{stg}	Storage Temperature Range			−65 to +150	°C
θ_{JA}	Thermal Resistance (Junction−to−Ambient)	0 lfpm 500 lfpm	SOIC−8 SOIC−8	190 130	°C/W °C/W
θ_{JC}	Thermal Resistance (Junction−to−Case)	Standard Board	SOIC−8	41 to 44	°C/W
θ_{JA}	Thermal Resistance (Junction−to−Ambient)	0 lfpm 500 lfpm	TSSOP−8 TSSOP−8	185 140	°C/W °C/W
θ_{JC}	Thermal Resistance (Junction−to−Case)	Standard Board	TSSOP−8	41 to 44	°C/W
θ_{JA}	Thermal Resistance (Junction−to−Ambient)	0 lfpm 500 lfpm	DFN8 DFN8	129 84	°C/W °C/W
θ_{JC}	Thermal Resistance (Junction−to−Case)	(Note 2)	DFN8	35 to 40	°C/W
T_{sol}	Wave Solder Pb Pb−Free			265 265	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

2. JEDEC standard multilayer board − 2S2P (2 signal, 2 power).

Table 5. 10EP DC CHARACTERISTICS, PECL V_{CC} = 3.3 V, V_{EE} = 0 V (Note 3)

		−40°C			25°C			85°C			
Symbol	Characteristic	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Unit
I_{EE}	Power Supply Current	26	34	44	26	35	45	28	37	47	mA
V_{OH}	Output HIGH Voltage (Note 4)	2165	2290	2415	2230	2355	2480	2290	2415	2540	mV
V_{OL}	Output LOW Voltage (Note 4)	1365	1490	1615	1430	1555	1680	1490	1615	1740	mV
V_{IH}	Input HIGH Voltage (Single−Ended)	2090		2415	2155		2480	2215		2540	mV
V_{IL}	Input LOW Voltage (Single−Ended)	1365		1690	1430		1755	1490		1815	mV
V_{IHCMR}	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 5)	2.0		3.3	2.0		3.3	2.0		3.3	V
I_{IH}	Input HIGH Current			150			150			150	μA
I_{IL}	Input LOW Current	0.5			0.5			0.5			μA

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm.

3. Input and output parameters vary 1:1 with V_{CC}. V_{EE} can vary +0.3 V to −2.2 V.
4. All loading with 50 Ω to V_{CC} − 2.0 V.
5. V_{IHCMR} min varies 1:1 with V_{EE}, V_{IHCMR} max varies 1:1 with V_{CC}. The V_{IHCMR} range is referenced to the most positive side of the differential input signal.

Table 6. 10EP DC CHARACTERISTICS, PECL V_{CC} = 5.0 V, V_{EE} = 0 V (Note 6)

Symbol	Characteristic	−40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
I_{EE}	Power Supply Current	26	34	44	26	35	45	28	37	47	mA
V_{OH}	Output HIGH Voltage (Note 7)	3865	3990	4115	3930	4055	4180	3990	4115	4240	mV
V_{OL}	Output LOW Voltage (Note 7)	3065	3190	3315	3130	3255	3380	3190	3315	3440	mV
V_{IH}	Input HIGH Voltage (Single−Ended)	3790		4115	3855		4180	3915		4240	mV
V_{IL}	Input LOW Voltage (Single−Ended)	3065		3390	3130		3455	3190		3515	mV
V_{IHCMR}	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 8)	2.0		5.0	2.0		5.0	2.0		5.0	V
I_{IH}	Input HIGH Current			150			150			150	μA
I_{IL}	Input LOW Current	0.5			0.5			0.5			μA

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm.

6. Input and output parameters vary 1:1 with V_{CC}. V_{EE} can vary +2.0 V to −0.5 V.
7. All loading with 50 Ω to V_{CC} − 2.0 V.
8. V_{IHCMR} min varies 1:1 with V_{EE}, V_{IHCMR} max varies 1:1 with V_{CC}. The V_{IHCMR} range is referenced to the most positive side of the differential input signal.

Table 7. 10EP DC CHARACTERISTICS, NECL V_{CC} = 0 V; V_{EE} = −5.5 V to −3.0 V (Note 9)

Symbol	Characteristic	−40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
I_{EE}	Power Supply Current	23	30	40	23	30	40	23	30	40	mA
I_{EE}	Power Supply Current	26	34	44	26	35	45	28	37	47	mA
VOH	Output HIGH Voltage (Note 10)	−1135	−1010	−885	−1070	−945	−820	−1010	−885	−760	mV
V_{OL}	Output LOW Voltage (Note 10)	−1935	−1810	−1685	−1870	−1745	−1620	−1810	−1685	−1560	mV
V_{IH}	Input HIGH Voltage (Single−Ended)	−1210		−885	−1145		−820	−1085		−760	mV
V_{IL}	Input LOW Voltage (Single−Ended)	−1935		−1610	−1870		−1545	−1810		−1485	mV
V_{IHCMR}	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 11)	V_{EE} + 2.0		0.0	V_{EE} + 2.0		0.0	V_{EE} + 2.0		0.0	V
I_{IH}	Input HIGH Current			150			150			150	μA
I_{IL}	Input LOW Current	0.5			0.5			0.5			μA

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm.

9. Input and output parameters vary 1:1 with V_{CC}.
10. All loading with 50 Ω to V_{CC} − 2.0 V.
11. V_{IHCMR} min varies 1:1 with V_{EE}, V_{IHCMR} max varies 1:1 with V_{CC}. The V_{IHCMR} range is referenced to the most positive side of the differential input signal.

Table 8. 100EP DC CHARACTERISTICS, PECL V_{CC} = 3.3 V, V_{EE} = 0 V (Note 12)

Symbol	Characteristic	−40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
I_{EE}	Power Supply Current	26	34	44	26	35	45	28	37	47	mA
V_{OH}	Output HIGH Voltage (Note 13)	2155	2280	2405	2155	2280	2405	2155	2280	2405	mV
V_{OL}	Output LOW Voltage (Note 13)	1355	1480	1605	1355	1480	1605	1355	1480	1605	mV
V_{IH}	Input HIGH Voltage (Single−Ended)	2075		2420	2075		2420	2075		2420	mV
V_{IL}	Input LOW Voltage (Single−Ended)	1355		1675	1355		1675	1355		1675	mV
V_{IHCMR}	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 14)	2.0		3.3	2.0		3.3	2.0		3.3	V
I_{IH}	Input HIGH Current			150			150			150	μA
I_{IL}	Input LOW Current	0.5			0.5			0.5			μA

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm.

12. Input and output parameters vary 1:1 with V_{CC}. V_{EE} can vary +0.3 V to −2.2 V.
13. All loading with 50 Ω to V_{CC} − 2.0 V.
14. V_{IHCMR} min varies 1:1 with V_{EE}, V_{IHCMR} max varies 1:1 with V_{CC}. The V_{IHCMR} range is referenced to the most positive side of the differential input signal.

Table 9. 100EP DC CHARACTERISTICS, PECL V_{CC} = 5.0 V, V_{EE} = 0 V (Note 15)

Symbol	Characteristic	−40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
I_{EE}	Power Supply Current	26	34	44	26	35	45	28	37	47	mA
V_{OH}	Output HIGH Voltage (Note 16)	3855	3980	4105	3855	3980	4105	3855	3980	4105	mV
V_{OL}	Output LOW Voltage (Note 16)	3055	3180	3305	3055	3180	3305	3055	3180	3305	mV
V_{IH}	Input HIGH Voltage (Single−Ended)	3775		4120	3775		4120	3775		4120	mV
V_{IL}	Input LOW Voltage (Single−Ended)	3055		3375	3055		3375	3055		3375	mV
V_{IHCMR}	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 17)	2.0		5.0	2.0		5.0	2.0		5.0	V
I_{IH}	Input HIGH Current			150			150			150	μA
I_{IL}	Input LOW Current	0.5			0.5			0.5			μA

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm.

15. Input and output parameters vary 1:1 with V_{CC}. V_{EE} can vary +2.0 V to −0.5 V.
16. All loading with 50 Ω to V_{CC} − 2.0 V.
17. V_{IHCMR} min varies 1:1 with V_{EE}, V_{IHCMR} max varies 1:1 with V_{CC}. The V_{IHCMR} range is referenced to the most positive side of the differential input signal.

Table 10. 100EP DC CHARACTERISTICS, NECL V_{CC} = 0 V; V_{EE} = −5.5 V to −3.0 V (Note 18)

Symbol	Characteristic	−40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
I_{EE}	Power Supply Current	26	34	44	26	35	45	28	37	47	mA
V_{OH}	Output HIGH Voltage (Note 19)	−1145	−1020	−895	−1145	−1020	−895	−1145	−1020	−895	mV
V_{OL}	Output LOW Voltage (Note 19)	−1945	−1820	−1695	−1945	−1820	−1695	−1945	−1820	−1695	mV
V_{IH}	Input HIGH Voltage (Single−Ended)	−1225		−880	−1225		−880	−1225		−880	mV
V_{IL}	Input LOW Voltage (Single−Ended)	−1945		−1625	−1945		−1625	−1945		−1625	mV
V_{IHCMR}	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 20)	V_{EE} + 2.0		0.0	V_{EE} + 2.0		0.0	V_{EE} + 2.0		0.0	V
I_{IH}	Input HIGH Current			150			150			150	μA
I_{IL}	Input LOW Current	0.5			0.5			0.5			μA

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm.

18. Input and output parameters vary 1:1 with V_{CC}.
19. All loading with 50 Ω to V_{CC} − 2.0 V.
20. V_{IHCMR} min varies 1:1 with V_{EE}, V_{IHCMR} max varies 1:1 with V_{CC}. The V_{IHCMR} range is referenced to the most positive side of the differential input signal.

Table 11. AC CHARACTERISTICS V_{CC} = 0 V; V_{EE} = −3.0 V to −5.5 V or V_{CC} = 3.0 V to 5.5 V; V_{EE} = 0 V (Note 21)

Symbol	Characteristic	−40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
f_{max}	Maximum Frequency (Figure 2)		> 3			> 3			> 3		GHz
t_{PLH}, t_{PHL}	Propagation Delay to Output Differential CLK, $\overline{CLK}$ to Q, $\overline{Q}$ 10	250	300	350	270	320	370	300	350	420	ps
	100	275	340	425	300	375	450	350	425	500	
	RESET to Q, $\overline{Q}$	300	380	450	325	400	475	350	425	500	
t_{RR}	Reset Recovery	150			150			150			ps
t_S	Setup Time	100			100	80		100			ps
t_H	Hold Time	100			100	40		100			
t_{PW}	Minimum Pulse Width RESET	500	440		500	440		500	440		ps
t_{JITTER}	Cycle−to−Cycle Jitter (Figure 2)		0.2	< 1		0.2	< 1		0.2	< 1	ps
t_r	Output Rise/Fall Times Q, $\overline{Q}$										ps
t_f	(20% − 80%)	70	120	170	80	130	180	100	150	200	

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm.

21. Measured using a 750 mV source, 50% duty cycle clock source. All loading with 50 Ω to V_{CC} − 2.0 V.

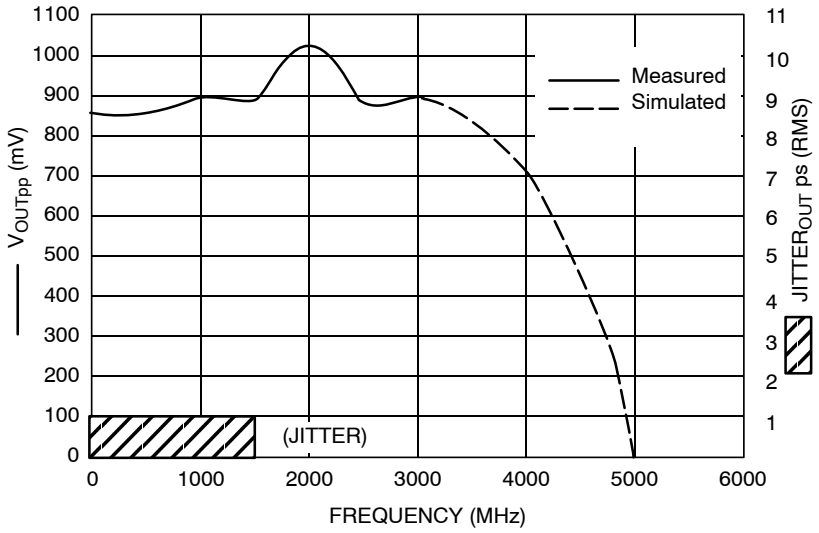


Figure 2. F_{max}/Jitter

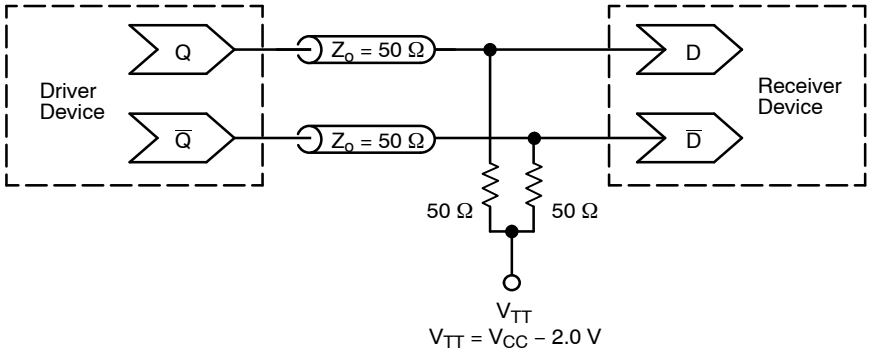


Figure 3. Typical Termination for Output Driver and Device Evaluation (See Application Note AND8020/D – Termination of ECL Logic Devices.)

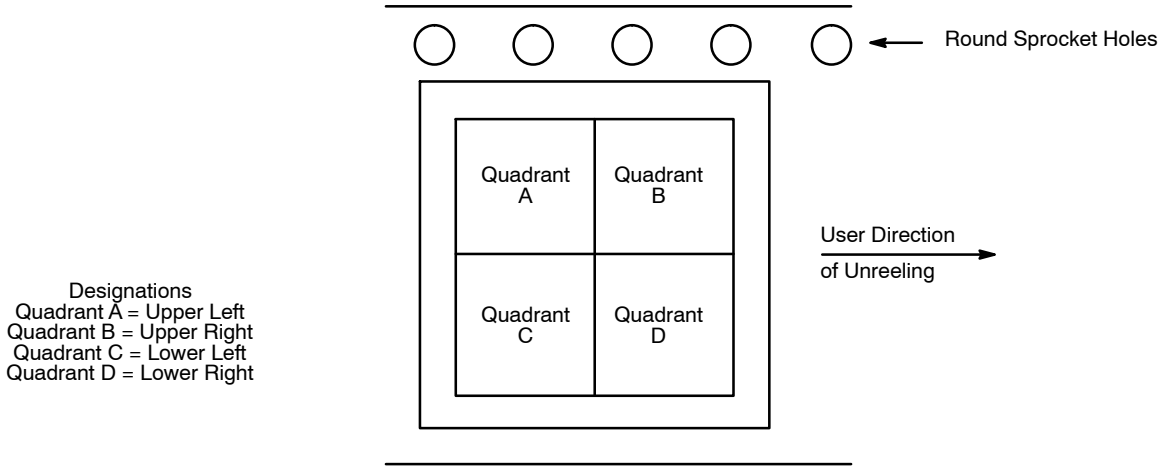


Figure 4. Tape and Reel Pin 1 Quadrant Orientation

ORDERING INFORMATION

Device	Package	Shipping†
MC10EP51DR2G	SOIC−8 (Pb−Free)	2500 / Tape & Reel
MC10EP51MNTAG	DFN8 (Pb−Free)	1000 / Tape & Reel (Pin 1 Orientation in Quadrant A, Figure 4)
MC100EP51DG	SOIC−8 (Pb−Free)	98 Units / Rail
MC100EP51DR2G	SOIC−8 (Pb−Free)	2500 / Tape & Reel
MC100EP51DTG	TSSOP−8 (Pb−Free)	100 Units / Rail
MC100EP51DTR2G	TSSOP−8 (Pb−Free)	2500 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

DISCONTINUED (Note 22)

Device	Package	Shipping†
MC10EP51DG	SOIC−8 (Pb−Free)	98 Units / Rail
MC10EP51DTG	TSSOP−8 (Pb−Free)	100 Units / Rail

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

22. **DISCONTINUED:** This device is not recommended for new design. Please contact your **onsemi** representative for information. The most current information on this device may be available on www.onsemi.com.

Resource Reference of Application Notes

AN1405/D – ECL Clock Distribution Techniques

AN1406/D – Designing with PECL (ECL at +5.0 V)

AN1503/D – ECLinPS™ I/O SPiCE Modeling Kit

AN1504/D – Metastability and the ECLinPS Family

AN1568/D – Interfacing Between LVDS and ECL

AN1672/D – The ECL Translator Guide

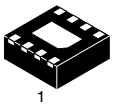
AND8001/D – Odd Number Counters Design

AND8002/D – Marking and Date Codes

AND8020/D – Termination of ECL Logic Devices

AND8066/D – Interfacing with ECLinPS

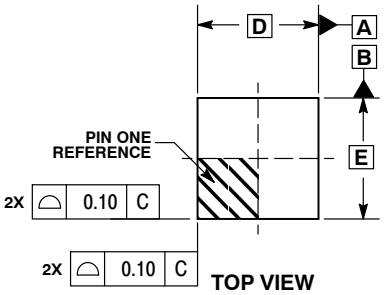
AND8090/D – AC Characteristics of ECL Devices

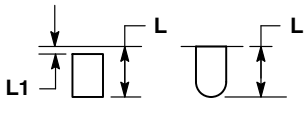


SCALE 4:1

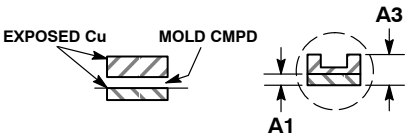
DFN8 2x2, 0.5P
CASE 506AA
ISSUE F

DATE 04 MAY 2016





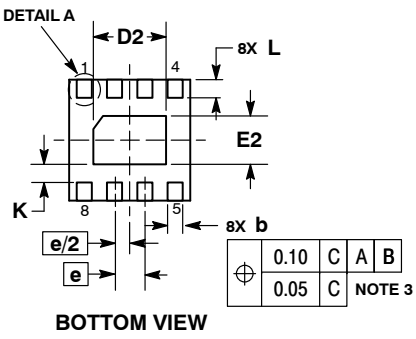
DETAIL A
OPTIONAL CONSTRUCTIONS



DETAIL B
ALTERNATE CONSTRUCTIONS

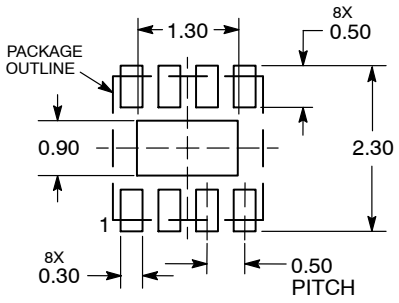
NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994 .
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.20 MM FROM TERMINAL TIP.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

	MILLIMETERS	
DIM	MIN	MAX
A	0.80	1.00
A1	0.00	0.05
A3	0.20 REF	
b	0.20	0.30
D	2.00 BSC	
D2	1.10	1.30
E	2.00 BSC	
E2	0.70	0.90
e	0.50 BSC	
K	0.30 REF	
L	0.25	0.35
L1	---	0.10



BOTTOM VIEW

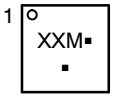
RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb−Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



XX = Specific Device Code
M = Date Code
▪ = Pb−Free Device

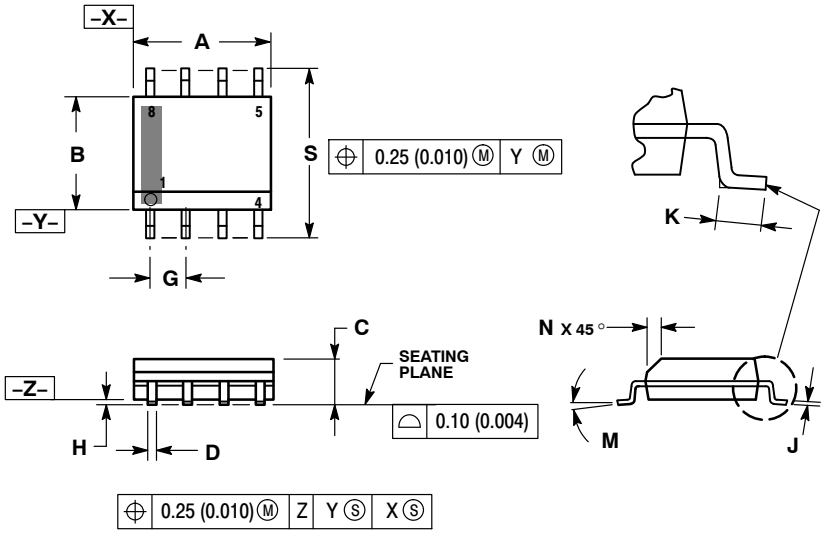
*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “▪”, may or may not be present. Some products may not follow the Generic Marking.

DOCUMENT NUMBER:	**98AON18658D**	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped “CONTROLLED COPY” in red.	
DESCRIPTION:	**DFN8, 2.0X2.0, 0.5MM PITCH**		**PAGE 1 OF 1**

SCALE 1:1

SOIC−8 NB
CASE 751−07
ISSUE AK

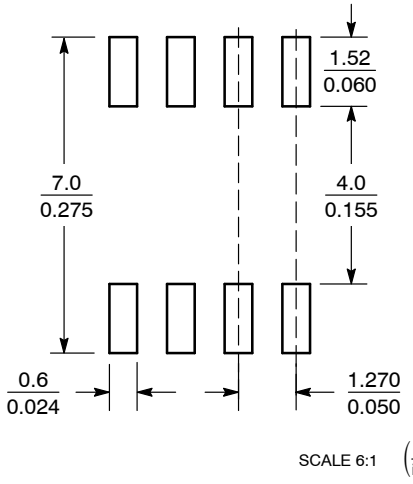
DATE 16 FEB 2011



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. 751−01 THRU 751−06 ARE OBSOLETE. NEW STANDARD IS 751−07.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	4.80	5.00	0.189	0.197
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.053	0.069
D	0.33	0.51	0.013	0.020
G	1.27 BSC		0.050 BSC	
H	0.10	0.25	0.004	0.010
J	0.19	0.25	0.007	0.010
K	0.40	1.27	0.016	0.050
M	0°	8°	0°	8°
N	0.25	0.50	0.010	0.020
S	5.80	6.20	0.228	0.244

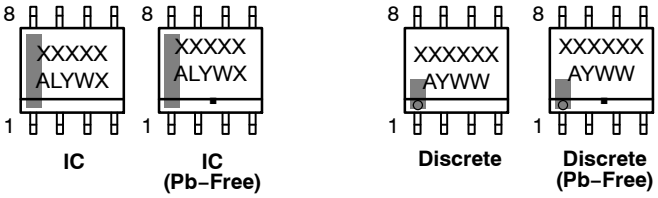
SOLDERING FOOTPRINT*



SCALE 6:1 (mm / inches)

*For additional information on our Pb−Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



XXXXX = Specific Device Code
A = Assembly Location
L = Wafer Lot
Y = Year
W = Work Week
▪ = Pb−Free Package

XXXXXX = Specific Device Code
A = Assembly Location
Y = Year
WW = Work Week
▪ = Pb−Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

STYLES ON PAGE 2

DOCUMENT NUMBER:	**98ASB42564B**	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.	
DESCRIPTION:	**SOIC−8 NB**		**PAGE 1 OF 2**

SOIC−8 NB
CASE 751−07
ISSUE AK

DATE 16 FEB 2011

STYLE 1:
PIN 1. EMITTER
2. COLLECTOR
3. COLLECTOR
4. EMITTER
5. EMITTER
6. BASE
7. BASE
8. EMITTER

STYLE 2:
PIN 1. COLLECTOR, DIE, #1
2. COLLECTOR, #1
3. COLLECTOR, #2
4. COLLECTOR, #2
5. BASE, #2
6. EMITTER, #2
7. BASE, #1
8. EMITTER, #1

STYLE 3:
PIN 1. DRAIN, DIE #1
2. DRAIN, #1
3. DRAIN, #2
4. DRAIN, #2
5. GATE, #2
6. SOURCE, #2
7. GATE, #1
8. SOURCE, #1

STYLE 4:
PIN 1. ANODE
2. ANODE
3. ANODE
4. ANODE
5. ANODE
6. ANODE
7. ANODE
8. COMMON CATHODE

STYLE 5:
PIN 1. DRAIN
2. DRAIN
3. DRAIN
4. DRAIN
5. GATE
6. GATE
7. SOURCE
8. SOURCE

STYLE 6:
PIN 1. SOURCE
2. DRAIN
3. DRAIN
4. SOURCE
5. SOURCE
6. GATE
7. GATE
8. SOURCE

STYLE 7:
PIN 1. INPUT
2. EXTERNAL BYPASS
3. THIRD STAGE SOURCE
4. GROUND
5. DRAIN
6. GATE 3
7. SECOND STAGE Vd
8. FIRST STAGE Vd

STYLE 8:
PIN 1. COLLECTOR, DIE #1
2. BASE, #1
3. BASE, #2
4. COLLECTOR, #2
5. COLLECTOR, #2
6. EMITTER, #2
7. EMITTER, #1
8. COLLECTOR, #1

STYLE 9:
PIN 1. EMITTER, COMMON
2. COLLECTOR, DIE #1
3. COLLECTOR, DIE #2
4. EMITTER, COMMON
5. EMITTER, COMMON
6. BASE, DIE #2
7. BASE, DIE #1
8. EMITTER, COMMON

STYLE 10:
PIN 1. GROUND
2. BIAS 1
3. OUTPUT
4. GROUND
5. GROUND
6. BIAS 2
7. INPUT
8. GROUND

STYLE 11:
PIN 1. SOURCE 1
2. GATE 1
3. SOURCE 2
4. GATE 2
5. DRAIN 2
6. DRAIN 2
7. DRAIN 1
8. DRAIN 1

STYLE 12:
PIN 1. SOURCE
2. SOURCE
3. SOURCE
4. GATE
5. DRAIN
6. DRAIN
7. DRAIN
8. DRAIN

STYLE 13:
PIN 1. N.C.
2. SOURCE
3. SOURCE
4. GATE
5. DRAIN
6. DRAIN
7. DRAIN
8. DRAIN

STYLE 14:
PIN 1. N−SOURCE
2. N−GATE
3. P−SOURCE
4. P−GATE
5. P−DRAIN
6. P−DRAIN
7. N−DRAIN
8. N−DRAIN

STYLE 15:
PIN 1. ANODE 1
2. ANODE 1
3. ANODE 1
4. ANODE 1
5. CATHODE, COMMON
6. CATHODE, COMMON
7. CATHODE, COMMON
8. CATHODE, COMMON

STYLE 16:
PIN 1. EMITTER, DIE #1
2. BASE, DIE #1
3. EMITTER, DIE #2
4. BASE, DIE #2
5. COLLECTOR, DIE #2
6. COLLECTOR, DIE #2
7. COLLECTOR, DIE #1
8. COLLECTOR, DIE #1

STYLE 17:
PIN 1. VCC
2. V2OUT
3. V1OUT
4. TXE
5. RXE
6. VEE
7. GND
8. ACC

STYLE 18:
PIN 1. ANODE
2. ANODE
3. SOURCE
4. GATE
5. DRAIN
6. DRAIN
7. CATHODE
8. CATHODE

STYLE 19:
PIN 1. SOURCE 1
2. GATE 1
3. SOURCE 2
4. GATE 2
5. DRAIN 2
6. MIRROR 2
7. DRAIN 1
8. MIRROR 1

STYLE 20:
PIN 1. SOURCE (N)
2. GATE (N)
3. SOURCE (P)
4. GATE (P)
5. DRAIN
6. DRAIN
7. DRAIN
8. DRAIN

STYLE 21:
PIN 1. CATHODE 1
2. CATHODE 2
3. CATHODE 3
4. CATHODE 4
5. CATHODE 5
6. COMMON ANODE
7. COMMON ANODE
8. CATHODE 6

STYLE 22:
PIN 1. I/O LINE 1
2. COMMON CATHODE/VCC
3. COMMON CATHODE/VCC
4. I/O LINE 3
5. COMMON ANODE/GND
6. I/O LINE 4
7. I/O LINE 5
8. COMMON ANODE/GND

STYLE 23:
PIN 1. LINE 1 IN
2. COMMON ANODE/GND
3. COMMON ANODE/GND
4. LINE 2 IN
5. LINE 2 OUT
6. COMMON ANODE/GND
7. COMMON ANODE/GND
8. LINE 1 OUT

STYLE 24:
PIN 1. BASE
2. EMITTER
3. COLLECTOR/ANODE
4. COLLECTOR/ANODE
5. CATHODE
6. CATHODE
7. COLLECTOR/ANODE
8. COLLECTOR/ANODE

STYLE 25:
PIN 1. VIN
2. N/C
3. REXT
4. GND
5. IOUT
6. IOUT
7. IOUT
8. IOUT

STYLE 26:
PIN 1. GND
2. dv/dt
3. ENABLE
4. ILIMIT
5. SOURCE
6. SOURCE
7. SOURCE
8. VCC

STYLE 27:
PIN 1. ILIMIT
2. OVLO
3. UVLO
4. INPUT+
5. SOURCE
6. SOURCE
7. SOURCE
8. DRAIN

STYLE 28:
PIN 1. SW_TO_GND
2. DASIC_OFF
3. DASIC_SW_DET
4. GND
5. V_MON
6. VBULK
7. VBULK
8. VIN

STYLE 29:
PIN 1. BASE, DIE #1
2. EMITTER, #1
3. BASE, #2
4. EMITTER, #2
5. COLLECTOR, #2
6. COLLECTOR, #2
7. COLLECTOR, #1
8. COLLECTOR, #1

STYLE 30:
PIN 1. DRAIN 1
2. DRAIN 1
3. GATE 2
4. SOURCE 2
5. SOURCE 1/DRAIN 2
6. SOURCE 1/DRAIN 2
7. SOURCE 1/DRAIN 2
8. GATE 1

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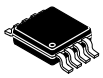
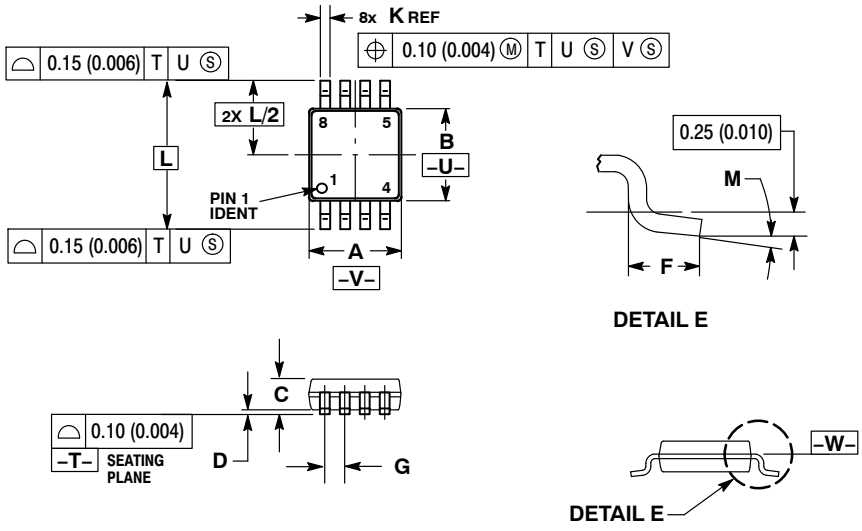
DESCRIPTION:	**SOIC−8 NB**		**PAGE 2 OF 2**



SCALE 2:1

TSSOP–8 3.00x3.00x0.95
CASE 948R–02
ISSUE A

DATE 07 APR 2000



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH. PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
6. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE –W–.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	2.90	3.10	0.114	0.122
B	2.90	3.10	0.114	0.122
C	0.80	1.10	0.031	0.043
D	0.05	0.15	0.002	0.006
F	0.40	0.70	0.016	0.028
G	0.65 BSC		0.026 BSC	
K	0.25	0.40	0.010	0.016
L	4.90 BSC		0.193 BSC	
M	0°	6°	0°	6°

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